

Hex Buffers

MC14049UB

The MC14049UB hex inverter/buffer is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. This complementary MOS device finds primary use where low power dissipation and/or high noise immunity is desired. This device provides logic-level conversion using only one supply voltage, V_{DD} . The input-signal high level (V_{IH}) can exceed the V_{DD} supply voltage for logic-level conversions. Two TTL/DTL Loads can be driven when the device is used as CMOS-to-TTL/DTL converters ($V_{DD} = 5.0$ V, $V_{OL} \leq 0.4$ V, $I_{OL} \geq 3.2$ mA). Note that pins 13 and 16 are not connected internally on this device; consequently connections to these terminals will not affect circuit operation.

Features

- High Source and Sink Currents
- High-to-Low Level Converter
- Supply Voltage Range = 3.0 V to 18 V
- Meets JEDEC UB Specifications
- V_{IN} can exceed V_{DD}
- Improved ESD Protection on All Inputs
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}	Input Voltage Range (DC or Transient)	-0.5 to +18.0	V
V_{out}	Output Voltage Range (DC or Transient)	-0.5 to V_{DD} +0.5	V
I_{in}	Input Current (DC or Transient) per Pin	± 10	mA
I_{out}	Output Current (DC or Transient) per Pin	+45	mA
P_D	Power Dissipation, per Package (Note 1)	825 740	mW
T_A	Ambient Temperature Range	-55 to +125	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature (8-Second Soldering)	260	°C

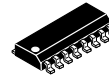
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: All Packages: See Figure 4.

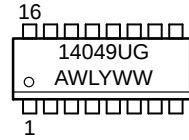
This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields referenced to the V_{SS} pin, only. Extra precautions must be taken to avoid applications of any voltage higher than the maximum rated voltages to this high-impedance circuit. For proper operation, the ranges $V_{SS} \leq V_{in} \leq 18$ V and $V_{SS} \leq V_{out} \leq V_{DD}$ are recommended.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

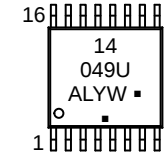
MARKING DIAGRAMS



SOIC-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F



A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

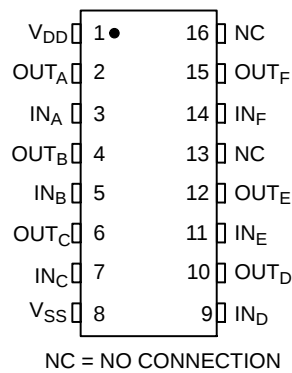


Figure 1. Pin Assignment

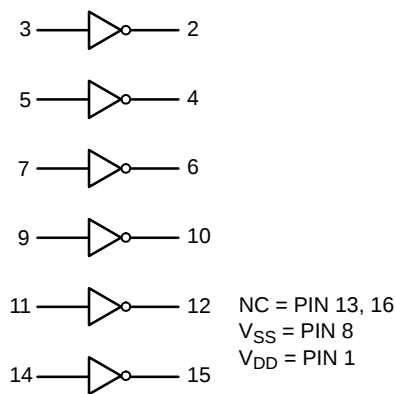


Figure 2. Logic Diagram
MC14049UB

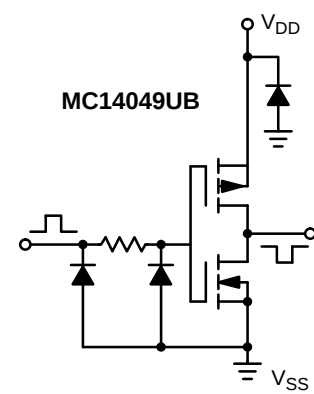


Figure 3. Circuit Schematic
(1/6 of circuit shown)

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	- 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V_{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
		15	-	0.05	-	0	0.05	-	0.05	
Output Voltage "1" Level $V_{in} = 0$ or V_{DD}	V_{OH}	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
		10	9.95	-	9.95	10	-	9.95	-	
		15	14.95	-	14.95	15	-	14.95	-	
Input Voltage "0" Level ($V_O = 4.5$ Vdc) ($V_O = 9.0$ Vdc) ($V_O = 13.5$ Vdc)	V_{IL}	5.0	-	1.0	-	2.25	1.0	-	1.0	Vdc
		10	-	2.0	-	4.50	2.0	-	2.0	
		15	-	2.5	-	6.75	2.5	-	2.5	
Input Voltage "1" Level ($V_O = 0.5$ Vdc) ($V_O = 1.0$ Vdc) ($V_O = 1.5$ Vdc)	V_{IH}	5.0	4.0	-	4.0	2.75	-	4.0	-	Vdc
		10	8.0	-	8.0	5.50	-	8.0	-	
		15	12.5	-	12.5	8.25	-	12.5	-	
Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc) ($V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Source I_{OH}	5.0	-1.6	-	-1.25	-2.5	-	-1.0	-	mAdc
		10	-1.6	-	-1.3	-2.6	-	-1.0	-	
		15	-4.7	-	-3.75	-10	-	-3.0	-	
Output Drive Current ($V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Sink I_{OL}	5.0	3.75	-	3.2	6.0	-	2.6	-	mAdc
		10	10	-	8.0	16	-	6.6	-	
		15	30	-	24	40	-	19	-	
Input Current	I_{in}	15	-	± 0.1	-	± 0.000 01	± 0.1	-	± 1.0	μ Adc
Input Capacitance ($V_{in} = 0$)	C_{in}	-	-	-	-	10	20	-	-	pF
Quiescent Current (Per Package)	I_{DD}	5.0	-	1.0	-	0.002	1.0	-	30	μ Adc
		10	-	2.0	-	0.004	2.0	-	60	
		15	-	4.0	-	0.006	4.0	-	120	
Total Supply Current (Note 3 and 4) (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs, all buffers switching)	I_T	5.0 10 15	$I_T = (1.8 \mu A/kHz) f + I_{DD}$ $I_T = (3.5 \mu A/kHz) f + I_{DD}$ $I_T = (5.3 \mu A/kHz) f + I_{DD}$							μ Adc

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.002$.

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (0.8 \text{ ns/pF}) C_L + 60 \text{ ns}$ $t_{TLH} = (0.3 \text{ ns/pF}) C_L + 35 \text{ ns}$ $t_{TLH} = (0.27 \text{ ns/pF}) C_L + 26.5 \text{ ns}$	t_{TLH}	5.0 10 15	– – –	100 50 40	160 100 60	ns
Output Fall Time $t_{THL} = (0.3 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{THL} = (0.12 \text{ ns/pF}) C_L + 14 \text{ ns}$ $t_{THL} = (0.1 \text{ ns/pF}) C_L + 10 \text{ ns}$	t_{THL}	5.0 10 15	– – –	40 20 15	60 40 30	ns
Propagation Delay Time $t_{PLH} = (0.38 \text{ ns/pF}) C_L + 61 \text{ ns}$ $t_{PLH} = (0.20 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{PLH} = (0.11 \text{ ns/pF}) C_L + 24.5 \text{ ns}$	t_{PLH}	5.0 10 15	– – –	80 40 30	120 65 50	ns
Propagation Delay Time $t_{PHL} = (0.38 \text{ ns/pF}) C_L + 11 \text{ ns}$ $t_{PHL} = (0.12 \text{ ns/pF}) C_L + 9 \text{ ns}$ $t_{PHL} = (0.11 \text{ ns/pF}) C_L + 4.5 \text{ ns}$	t_{PHL}	5.0 10 15	– – –	30 15 10	60 30 20	ns

5. The formulas given are for the typical characteristics only at 25°C .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14049UBDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14049UBDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NLV14049UBDR2G*		
MC14049UBDTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
NLV14049UBDTR2G*		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

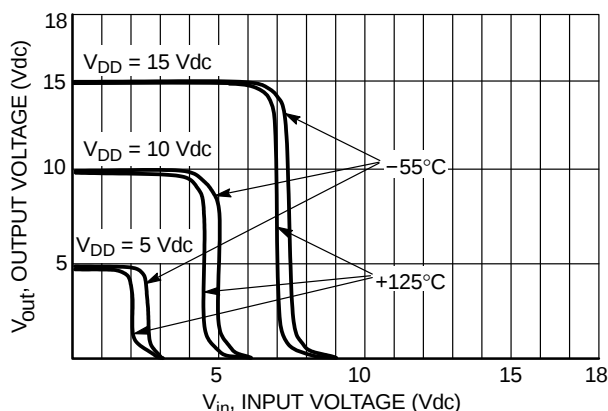


Figure 4. Typical Voltage Transfer Characteristics versus Temperature

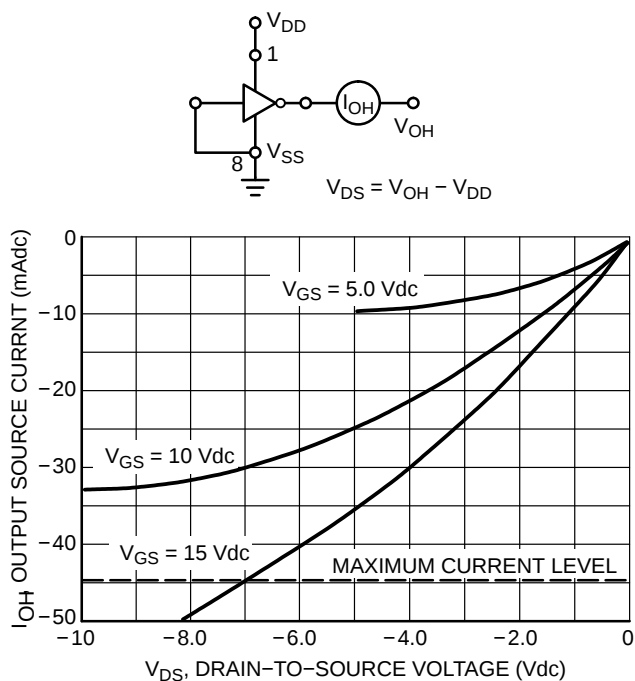


Figure 5. Typical Output Source Characteristics

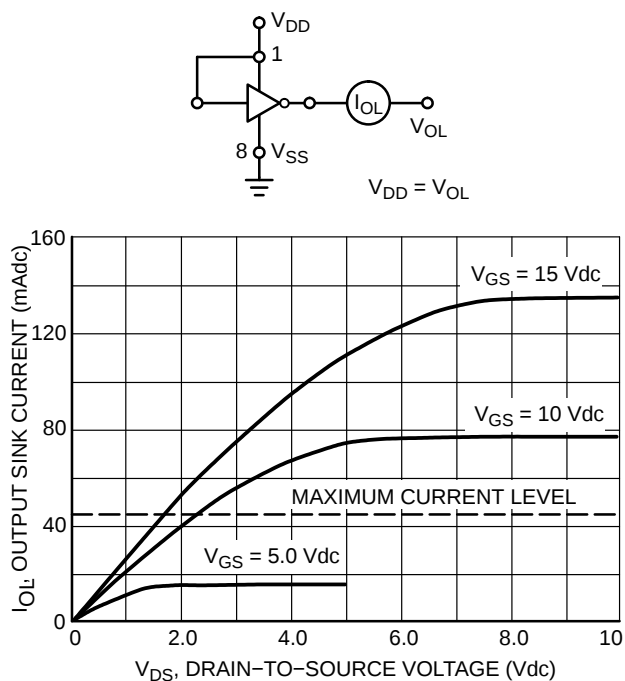


Figure 6. Typical Output Sink Characteristics

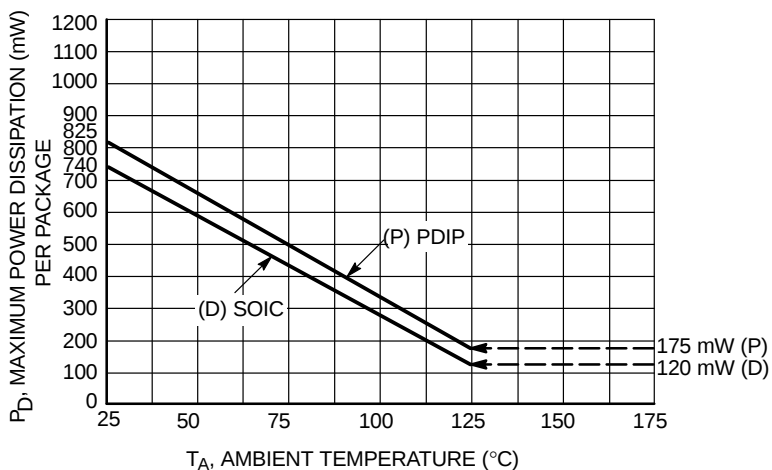


Figure 7. Ambient Temperature Power Derating

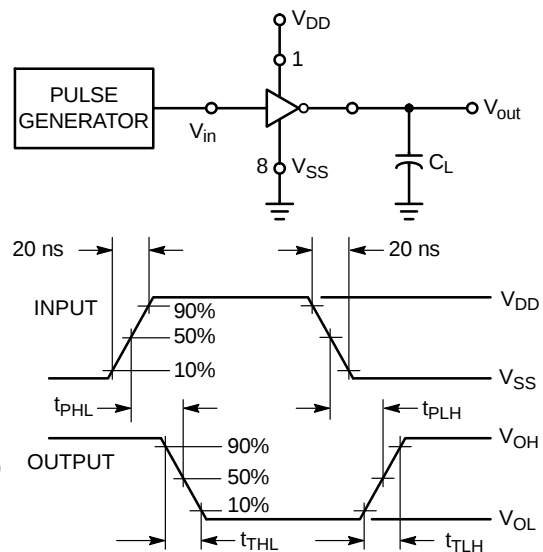
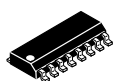


Figure 8. Switching Time Test Circuit and Waveforms

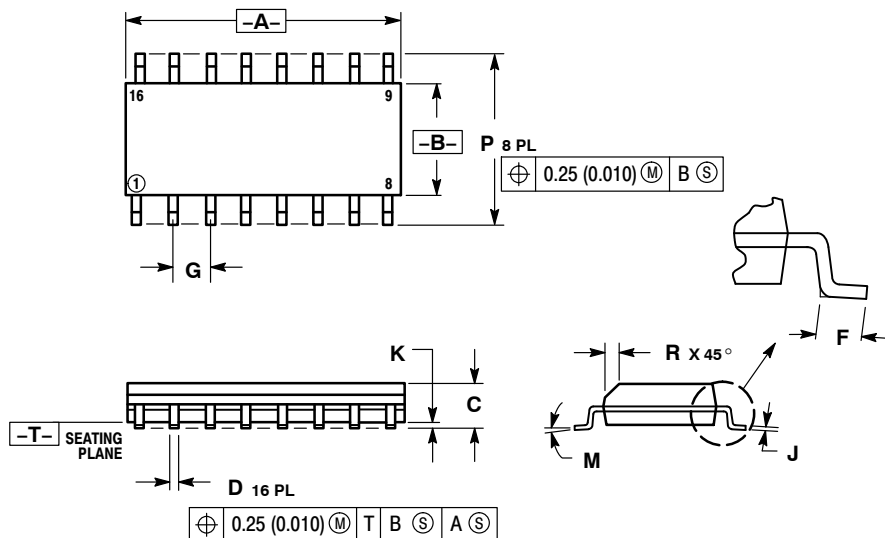
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



NOTES:

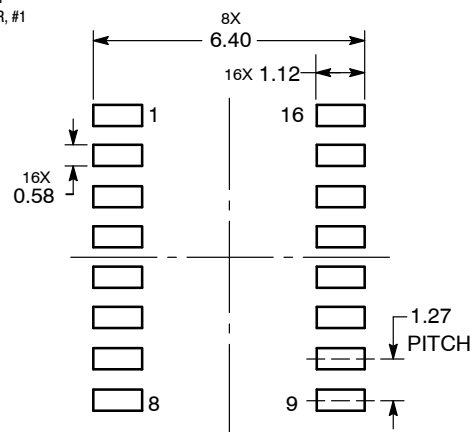
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:
PIN 1. COLLECTOR	PIN 1. CATHODE	PIN 1. COLLECTOR, DYE #1	PIN 1. COLLECTOR, DYE #1
2. BASE	2. ANODE	2. BASE, #1	2. COLLECTOR, #1
3. EMITTER	3. NO CONNECTION	3. EMITTER, #1	3. COLLECTOR, #2
4. NO CONNECTION	4. CATHODE	4. COLLECTOR, #1	4. COLLECTOR, #2
5. EMITTER	5. CATHODE	5. COLLECTOR, #2	5. COLLECTOR, #3
6. BASE	6. NO CONNECTION	6. BASE, #2	6. COLLECTOR, #3
7. COLLECTOR	7. ANODE	7. EMITTER, #2	7. COLLECTOR, #4
8. COLLECTOR	8. CATHODE	8. COLLECTOR, #2	8. COLLECTOR, #4
9. BASE	9. CATHODE	9. COLLECTOR, #3	9. BASE, #4
10. EMITTER	10. ANODE	10. BASE, #3	10. EMITTER, #4
11. NO CONNECTION	11. NO CONNECTION	11. EMITTER, #3	11. BASE, #3
12. EMITTER	12. CATHODE	12. COLLECTOR, #3	12. EMITTER, #3
13. BASE	13. CATHODE	13. COLLECTOR, #4	13. BASE, #2
14. COLLECTOR	14. NO CONNECTION	14. BASE, #4	14. EMITTER, #2
15. EMITTER	15. ANODE	15. EMITTER, #4	15. BASE, #1
16. COLLECTOR	16. CATHODE	16. COLLECTOR, #4	16. EMITTER, #1

STYLE 5:	STYLE 6:	STYLE 7:
PIN 1. DRAIN, DYE #1	PIN 1. CATHODE	PIN 1. SOURCE N-CH
2. DRAIN, #1	2. CATHODE	2. COMMON DRAIN (OUTPUT)
3. DRAIN, #2	3. CATHODE	3. COMMON DRAIN (OUTPUT)
4. DRAIN, #2	4. CATHODE	4. GATE P-CH
5. DRAIN, #3	5. CATHODE	5. COMMON DRAIN (OUTPUT)
6. DRAIN, #3	6. CATHODE	6. COMMON DRAIN (OUTPUT)
7. DRAIN, #4	7. CATHODE	7. COMMON DRAIN (OUTPUT)
8. DRAIN, #4	8. CATHODE	8. SOURCE P-CH
9. GATE, #4	9. ANODE	9. SOURCE P-CH
10. SOURCE, #4	10. ANODE	10. COMMON DRAIN (OUTPUT)
11. GATE, #3	11. ANODE	11. COMMON DRAIN (OUTPUT)
12. SOURCE, #3	12. ANODE	12. COMMON DRAIN (OUTPUT)
13. GATE, #2	13. ANODE	13. GATE N-CH
14. SOURCE, #2	14. ANODE	14. COMMON DRAIN (OUTPUT)
15. GATE, #1	15. ANODE	15. COMMON DRAIN (OUTPUT)
16. SOURCE, #1	16. ANODE	16. SOURCE N-CH

RECOMMENDED SOLDERING FOOTPRINT*



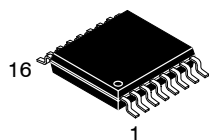
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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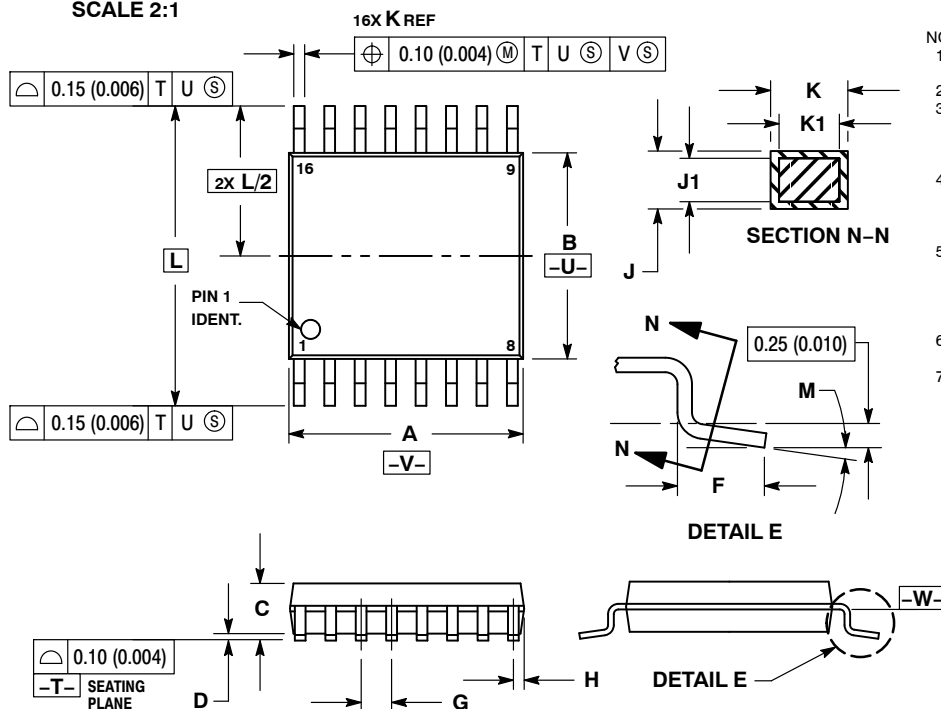
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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006

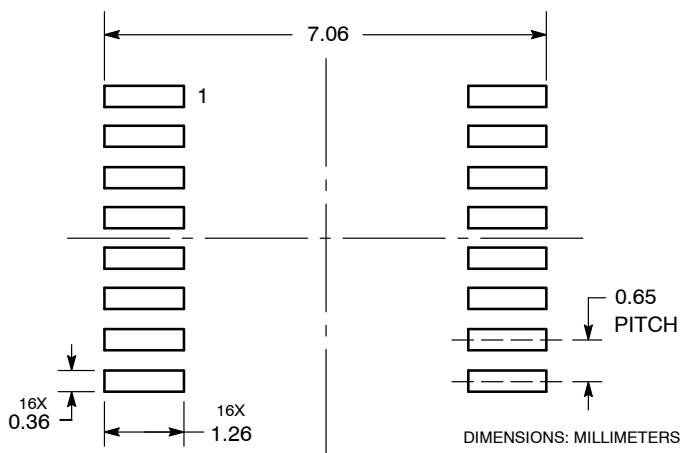


NOTES:

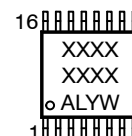
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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